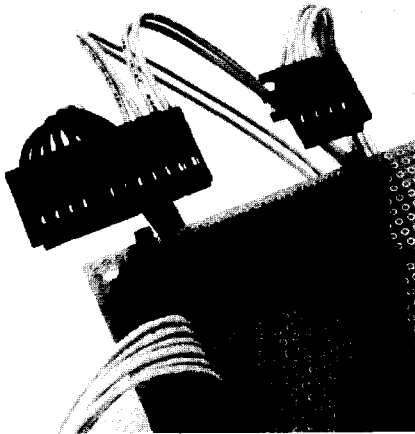


● **Modular Socket Housings**
2.5 mm Pitch

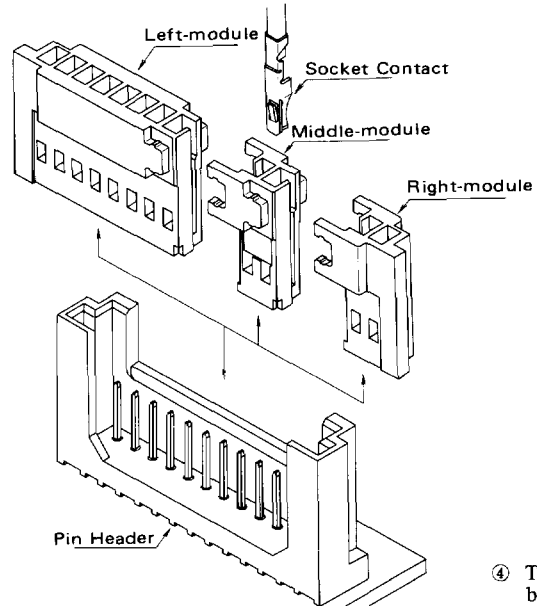
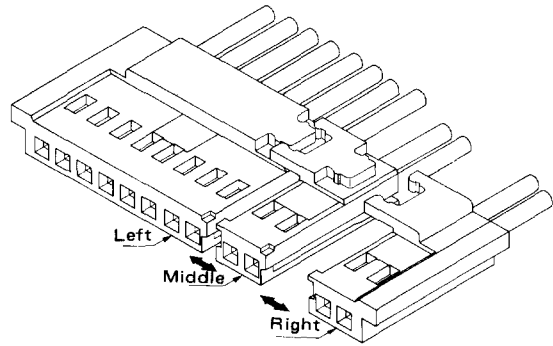
IL Series.Type B



The IL type B features its “modular” design of socket housings. This “modular” concept offers a considerable advantage in such application, for an example, where sub-assemblies of an equipment are made in different places. In such case, wiring can be done on each of the sub-assemblies with the modular socket connector blocks, and at the time of final assembly of the equipment the connector blocks are easily assembled to form a complete connector to mate with pin header on the p.c. board. Wiring can be done in each sub-assembly and in each specified direction of wires, without waiting until final process of equipment assembly, thus contributing to reduction of wiring/installation cost. Such direct connection of components to electronic circuit makes it possible to reduce number of components, and also standardization of wiring inside equipment can be done.

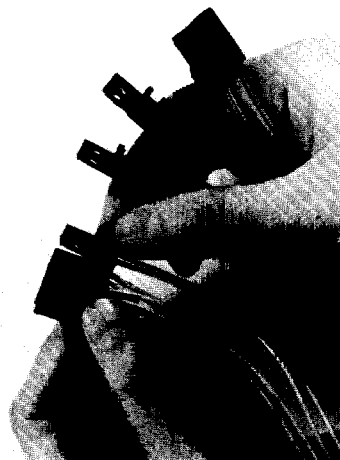
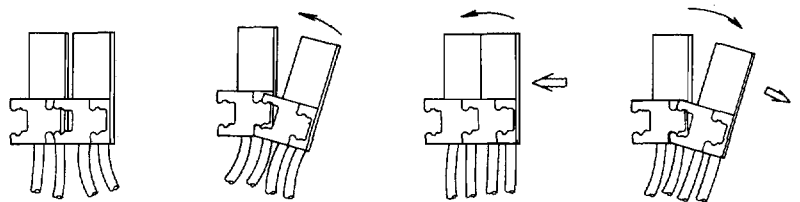
● **Materials & Finish**

Insulator: Nylon 66, UL94V-0, black
Pin Contact: Brass/Gold plating or tin plating
Socket contact: Copper alloy/Selective gold over nickel plating, or tin plating



Assembly Procedure

- ① Hold the connector blocks by hands
- ② Engage the lower portion of the blocks
- ③ Then, push the upper side portion of the blocks to complete assembly
- ④ To separate the blocks, pull the upper portion rotatingly to apart the blocks and then disengage the lower portion



(Ref.) Examples of Module Combination

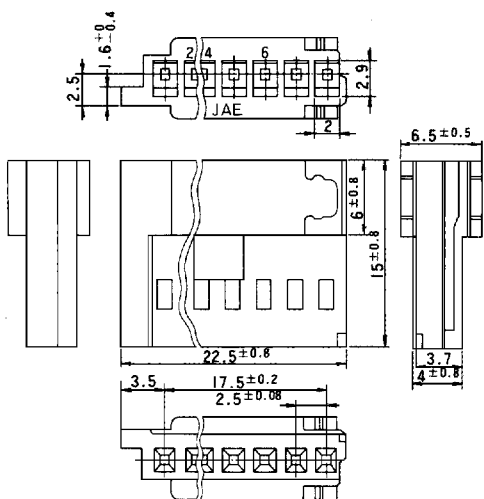
Left-side module is available in 8-contact layout, middle modules in 2- and 3-contact layouts and right-side modules in 2- and 4-contact layouts. Examples of module combination to form 12-, 16- and 20-contact connector assemblies are as shown below.

No. of Contacts/ Assy	Left-side 8-contact	Number of Modules/Assembly			
		Middle 2-contact	Middle 3-contact	Right-side 2-contact	Right-side 4-contact
12	1	1	-	1	-
	1	3	-	1	-
	1	-	2	1	-
16	1	2	-	-	1
	1	5	-	1	-
	1	2	2	1	-
20	1	4	-	-	1
	1	1	2	-	1

• Modular Socket Housings

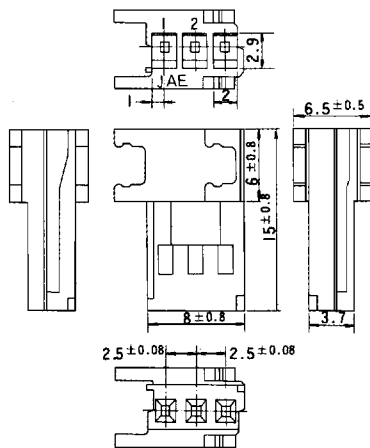
Left-side Module

8-contact/IL-B-8SL-S3C2

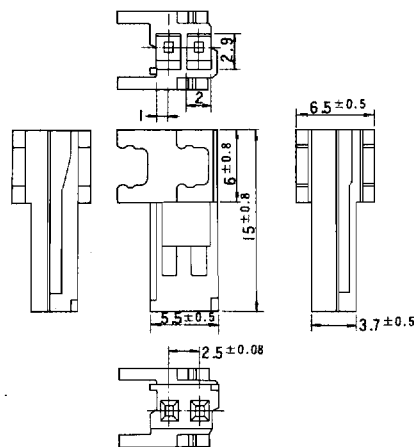


Middle Modules

3-contact/IL-B-3SM-S3C2-B

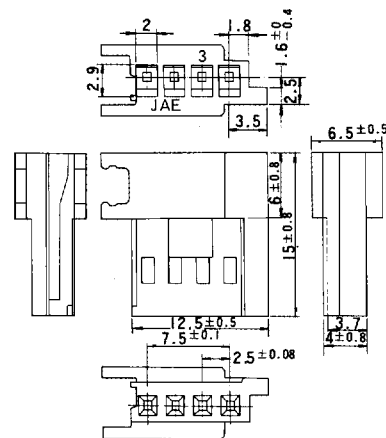


2-contact/IL-B-2SM-S3C2-B

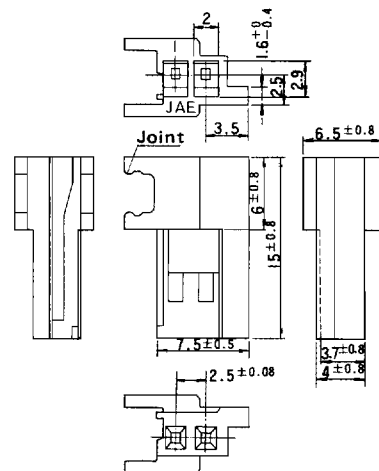


Right-side Modules

4-contact/IL-B-4SR-S3C2-B

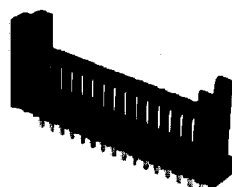
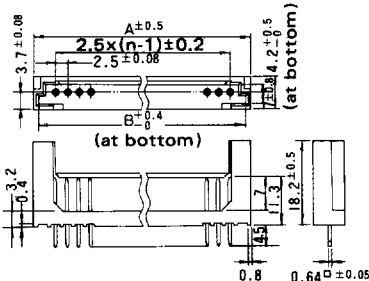


2-contact/IL-B-2SR-S3C2-B



• Straight Pin Header

IL-B- ** PA-S3T2-B**



• Crimp Socket Contacts

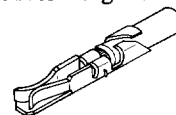
IL-C2-5000 (Tin Plate)

IL-C2-1-5000 (Selective Gold Plate)

Applicable Wire Size: AWG #28 ~ #22, stranded

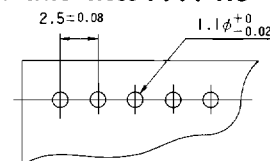
Wire conductor: 0.08 mm² ~ 0.32 mm²

Overall dia. including insulation: 1.0 ~ 1.7 mm



* See page 16 for details.

• P.C. Board Mounting Dimensions (Board thickness . . . 1.6 ~ 2.4 mm)



No. of Contacts	Gold Plated Contacts	Tin Plated Contacts	A	B
			+0.5	+0.4 -0
12	IL-B-12PA-S3T2-B1	IL-B-12PA-S3T2-B	36.7	34.6
16	IL-B-16PA-S3T2-B1	IL-B-16PA-S3T2-B	46.7	44.6
20	IL-B-20PA-S3T2-B1	IL-B-20PA-S3T2-B	56.7	54.6

(Note 1) Pin contact tip (chamfered portion) has no plating.
(Note 2) Bending in direction of each axis is 0.3 max.